



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

10-Apr-2006

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #15506

TITLE: Initial Notification of Qualification of OSPI for Assembly/Test of SO-8 MCM Package

EFFECTIVE DATE: 10-Aug-2006

AFFECTED CHANGE CATEGORY: ON Semiconductor Assembly and Test

AFFECTED PRODUCT DIVISION: Discrete

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Paul Alonas<s21008@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCEN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

Initial Process Change Notice to notify customers of the capacity expansion of the ON Semiconductor assembly/test location at Carmona, Philippines (OSPI) for 8/14/16 lead narrow SOIC packages. The devices listed on this IPCN have historically been assembled/tested at the ASE assembly/test facility located in Chung Li, Taiwan. At the expiration of this Initial PCN and subsequent Final PCN, these devices may be processed at either location. The ON Semiconductor facility at Carmona, Philippines is fully qualified and has been producing the SOIC narrow body products for many years. The capacity expansion will involve duplication of the existing equipment set currently in production



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QUALIFICATION PLAN:

AC/PC 121C, 15psig, 100%RH 96hrs
TC/PC -65/150C 500cycles
HTSL 150C 504hrs
Solderability 245C, 8hrs
Solder Heat 260C, 10sec
HAST/PC 130C, 85%RH 96hrs
Bond Pull Strength
Bond Shear

AFFECTED DEVICE LIST:

SRDA05-4R2
NUP4201DR2
LC03-6R2